

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20220121002.1 Qualify TI Chengdu (CDAT) as an additional Assembly site for select devices Change Notification / Sample Request

Date: March 02, 2022 **To:** Digi-Key PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (PCN_www_admin_team@list.ti.com). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team SC Business Services

20220121002.1 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LDC1312DNTR	null
LDC1312DNTT	null
LDC1612DNTR	null
LDC1612DNTT	null
LP55231SQE/NOPB	null
LP55231SQX/NOPB	null

Technical details of this Product Change follow on the next page(s).

PCN	PCN Number: 20220121002.1						PC	N Date:	March 02, 2022
Title: Qualify TI Chengdu (CDAT) as an additional Assembly site for select devices						levices			
Cus	tomer Contact:	PCN Manag	er		Dept:	Quality Se	ervio	ces	
Proposed 1 st Ship Jun 2, 202		2			Provided upon Request				
Change Type:									
			sign Wafer Bum		mp Site				
	Assembly Process Data		a Sheet		mp Material				
\boxtimes	Assembly Materials Part		number ch	nange		Wafer Bu	mp Process		
	Mechanical Specifi	anical Specification Test		Test	Site			Wafer Fal	b Site
	Packing/Shipping/	/Labeling Test		Process			Wafer Fal	b Materials	
	☐ Wafer Fab Process						b Process		
	PCN Details								

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Chengdu (CDAT) as an additional Assembly site for the list of devices shown below. Material differences between sites as follows.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City
TI Melaka	CU6	MYS	Melaka
TI Chengdu	CDA	CHN	Chengdu

Material Differences (Group 1 & 2):

	TI Melaka	TI Chengdu
Lead finish	Matte Sn	NiPdAu
Mold Compound	4208625	4222198

Upon expiry of this PCN TI will combine lead free solutions in a single standard part number, for the devices in groups 1 & 2. For example; <u>LDC1312DNTR</u> - can ship with both Matte Sn and NiPdAu.

Example:

- Customer order for 13,500 units of LDC1312DNTR with 4500 units SPQ (Standard Pack Quantity per Reel).
- TI can satisfy the above order in one of the following ways.
 - 3 Reels of NiPdAu finish. I.
 - 3 Reels of Matte Sn finish II.
 - 2 Reels of Matte Sn and 1 reel of NiPdAu finish. III.
 - 2 Reels of NiPdAu and 1 reel of Matte Sn finish. IV.

Group 2 Package Marking differences:

	TI Melaka	TI Chengdu
TI Bug	Include	Replace with "TI" text
Sample marking	LDC1612 LD 96U ARFE	LDC1612 TI 128 A2XS

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

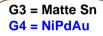
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☑ No Change			🛮 No Change

Changes to product identification resulting from this PCN:

Assembly Site		
TI Melaka	Assembly Site Origin (22L)	ASO: CU6
TI Chengdu	Assembly Site Origin (22L)	ASO: CDA

Sample product shipping label (not actual product label)





(1P) \$N74L\$07N\$R (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS

Group 1 Product Affected

LP55231SQE/NOPB LP55231SQX/NOPB

Group 2 Product Affected

LDC1312DNTR	LDC1312DNTT	LDC1612DNTR	LDC1612DNTT
LDCIJIZDNIK	LDCIJIZDNII	LDCIGIZDINIK	LDCIGIZDINI

Qualification Report

Approve Date 20-Dec-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: LDC1612DNTR	Qual Device: LP55231SQXNOPB	QBS Package Reference: BQ25890HRTWR	QBS Package Reference: CAXC8T245QRHLRQ1
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0

Туре	Test Name / Condition	Duration	Qual Device: LDC1612DNTR	Qual Device: LP55231SQXNOPB	QBS Package Reference: <u>BQ25890HRTWR</u>	QBS Package Reference: CAXC8T245QRHLRQ1
HTOL	Life Test, 125C	1000 Hours	-	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	3/135/0
HTSL	High Temp. Storage Bake 170C	420 Hours	3/231/0	-	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass
PD	Physical Dimensions	Cpk>1.67	-	-	-	3/90/0
SD	Solderability	Pb Free	3/66/0	3/66/0	-	-
тс	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
WBS	Bond Pull	Wires	3/228/0	3/228/0	3/228/0	3/90/0
WBP	Ball Bond Shear	Wires	3/228/0	3/228/0	3/228/0	3/9/0

- QBS: Qual By Similarity
- Qual Devices LDC1612DNTR and LP55231SQXNOPB are qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7 eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

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